[Name of Document] Claims

[Claim 1]

A sheet for semiconductor processing, the sheet comprising a base material and a pressure sensitive adhesive layer laminated on at least one surface of the base material,

the pressure sensitive adhesive layer being formed of a pressure sensitive adhesive composition, the pressure sensitive adhesive composition containing a polymer having a salt (excluding the metal alkoxide) and an energy ray curable group and an energy ray curable pressure sensitive adhesive component (excluding the polymer).

[Claim 2]

The sheet for semiconductor processing as recited in claim 1, wherein a content of the polymer in the pressure sensitive adhesive composition is 0.5 to 65 mass%.

[Claim 3]

The sheet for semiconductor processing as recited in claim 1 or 2, wherein a weight-average molecular weight of the polymer is 500 to 200,000.

[Claim 4]

The sheet for semiconductor processing as recited in any one of claims 1 to 3, wherein the polymer has a (meth) acryloyl group as the energy ray curable group.

[Claim 5]

The sheet for semiconductor processing as recited in any one of claims 1 to 4, wherein a content of the energy ray curable group per a unit mass of the polymer is 5×10^{-5} to 2×10^{-3} mol/g.

[Claim 6]

The sheet for semiconductor processing as recited in any one of claims 1 to 5, wherein the energy ray curable pressure sensitive adhesive component contains an acrylic-based polymer without energy ray curability and an energy ray curable compound.

[Claim 7]

The sheet for semiconductor processing as recited in any one of claims 1 to 5, wherein the energy ray curable pressure sensitive adhesive component contains an acrylic-based polymer having a side chain to which an energy ray curable group is introduced.

[Claim 8]

The sheet for semiconductor processing as recited in any one of claims 1 to 7, wherein the energy ray curable pressure sensitive adhesive component contains a cross-linker.

[Claim 9]

The sheet for semiconductor processing as recited in any one of claims 1 to 8, wherein the salt is a quaternary ammonium salt.

[Claim 10]

The sheet for semiconductor processing as recited in claim 6 or 7, wherein the acrylic-based polymer has an ether bond at a side chain.